

RF Amplifier for CD Players

Description

The CXA2568M is an IC developed for compact disc players. This IC incorporates an RF amplifier, focus error amplifier, tracking error amplifier, APC circuit and RF level control circuit. (The voltage-converted optical pickup output is supported.)

Features

- Low power consumption (50 mW at ± 2.5 V)
- High-band RF amplifier
- APC circuit
- RF level control circuit (Hold circuit included)
- Both single power supply and dual power supply operations possible.
- Compatible with pickup for LC and PD

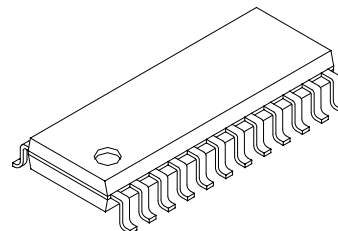
Applications

Compact disc players

Structure

Bipolar silicon monolithic IC

24 pin SOP (Plastic)

**Absolute Maximum Ratings** ($T_a=25$ °C)

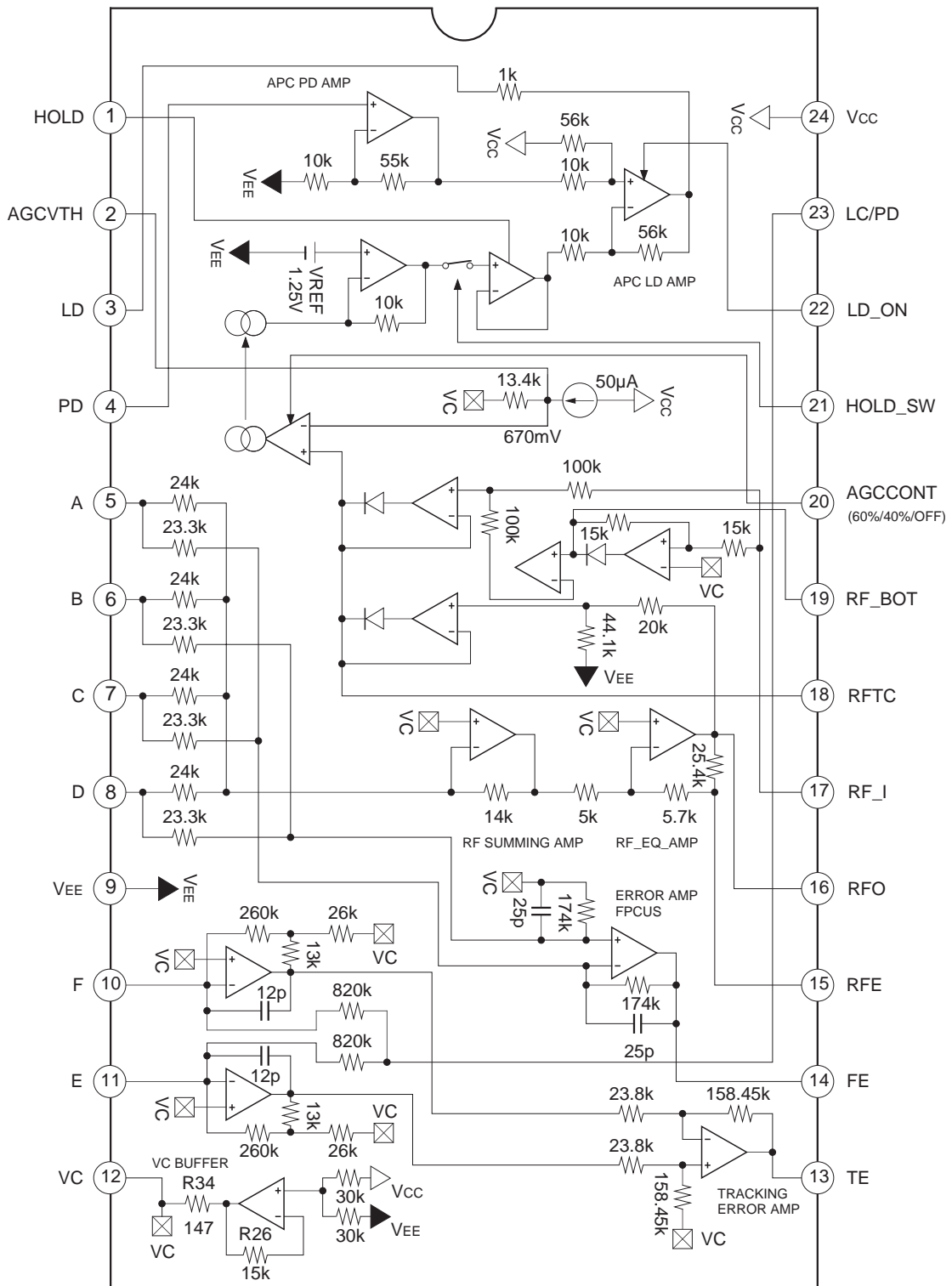
• Supply voltage	V_{CC}	12	V
• Operating temperature	T_{opr}	-20 to +75	°C
• Storage temperature	T_{stg}	-65 to +150	°C
• Allowable power dissipation	P_D	650	mW

Operating Conditions

Supply voltage	$V_{CC}-V_{EE}$	4.5 to 5.5	V
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Block Diagram and Pin Configuration



Pin Description

Pin No.	Symbol	IO	Equivalent circuit	Description
1	HOLD	—		External hold time-constant pin for RF level control.
2	AGCVTH	—		Variable pin of reference level for RF level control. The reference level can be varied by the external resistor.
3	LD	O		Output pin of APC amplifier.
4	PD	I		Input pin of APC amplifier.

Pin No.	Symbol	IO	Equivalent circuit	Description
5 6 7 8	A B C D	I I I I		Input pin of RF and FE amplifiers for Pins 5, 6, 7 and 8.
9	V _{EE}	—		V _{EE} .
10 11 23	TE E LC/PD	I I I		Input pin of tracking error amplifier for Pins 10 and 11. An external resistor for V-I conversion should be connected because these pins are for current input. Pin 23 is a bias for LC when connected to V _{cc} and for PD IC when left open.
12	VC	O		DC voltage output pin of $(V_{CC}+V_{EE})/2$. Connect to GND when dual power supply (± 2.5 V) is used; connect a smoothing capacitor when single power supply (+5 V) is used.

Pin No.	Symbol	IO	Equivalent circuit	Description
13	TE	O		Output pin of tracking error amplifier. The F-E signal is output.
14	FE	O		Output pin of focus error amplifier.
15	REF	—		Equalizing pin of RF amplifier. Frequency response can be adjusted by connecting CR to this pin.
16	RFO	O		Output pin of RF amplifier.
17	RF_I	I		Input pin of RF amplifier output RFO with capacitance coupled.

Pin No.	Symbol	IO	Equivalent circuit	Description
18	RFTC	—		External time-constant pin for RF level control.
19	RF_BOT	—		External bottom time-constant pin for RF level control.
20	AGCCONT	I		RF level control ON (limit level of 60 % / 40 %)/ OFF switching pin. 60 % for V _{CC} , 40 % for open or V _C and OFF for V _{EE} .
21	HOLD_SW	I		RF level control hold ON/OFF switching pin. ON for V _{CC} and OFF for V _{EE} .
22	LD ON	I		ON/OFF switching pin of APC amplifier. ON for V _{CC} and OFF for V _{EE} .
24	V _{CC}	—		V _{CC}

Electrical Characteristics

± 2.5 V power supply ($V_{CC}=2.5$ V, $V_{EE}=-2.5$ V, $V_C=GND$)

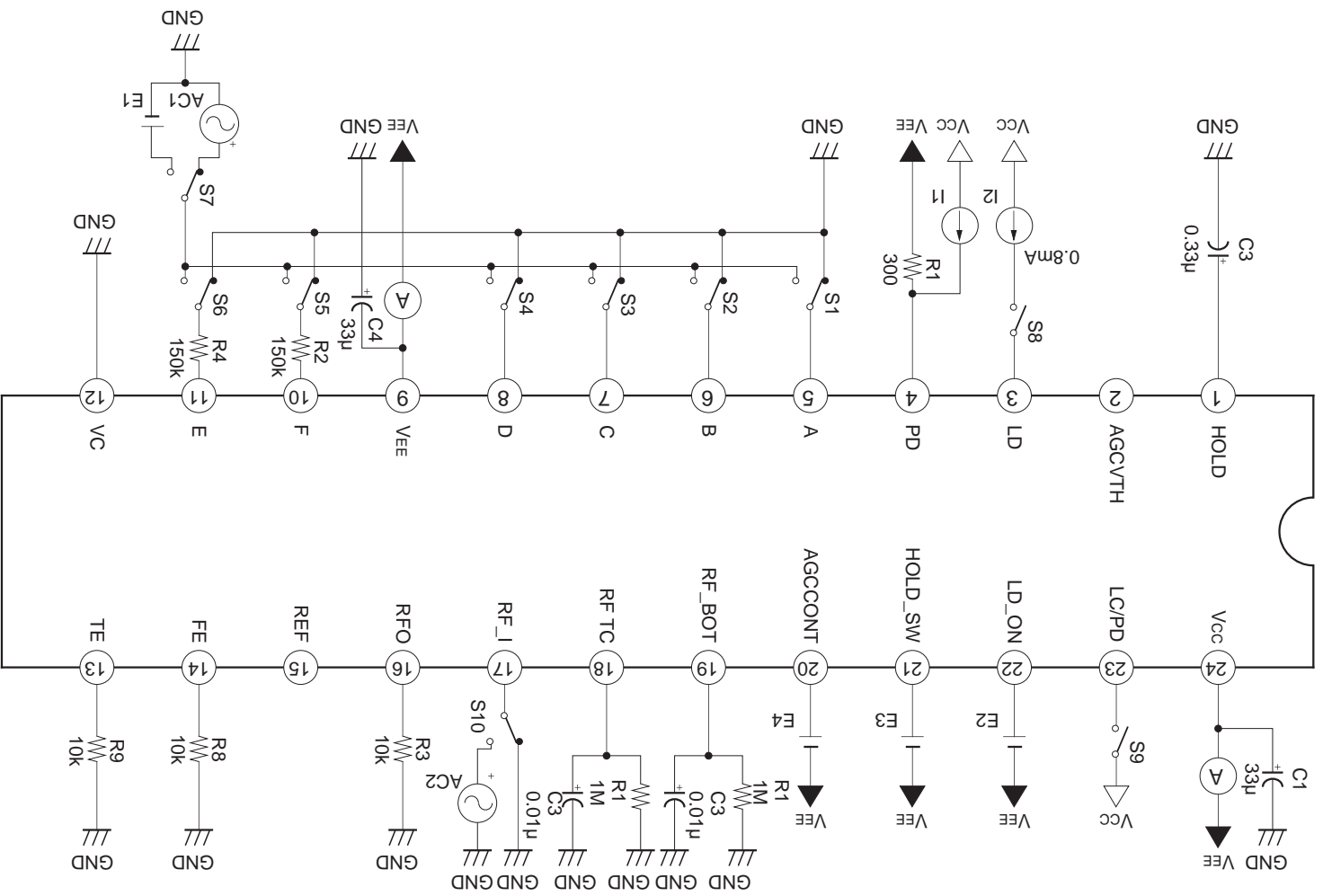
Measurement No.	Measurement item	Symbol	SW conditions										Bias conditions							Measurement pin	Description of I/O waveform and measurement method		Min.	Typ.	Max.	Unit
			1	2	3	4	5	6	7	8	9	10	E1	E2	E3	E4	AC1	AC2	I1							
1	Current consumption	ICC																	24	Input GND		6.5	10	13.5	mA	
2		IEE																		9	Input GND		-13.5	-10	-6.5	mA
3	RF amplifier	Offset voltage 1																	16	Input GND	Output DC measurement	-25	0	25	mV	
4		Voltage gain	V16-2	O	O	O	O									1 kHz 100 mVp-p				16		Output AC measurement	19.9	22.9	25.9	dB
5		Maximum output amplitude H	V16-3	O	O	O	O			O					280 mV					16		Output DC measurement	2.2	—	—	V
6		Maximum output amplitude L	V16-4	O	O	O	O			O					-280 mV					16		Output DC measurement	—	—	-2	V
7	FE amplifier	Offset voltage																	14	Input GND	Output DC measurement	-30.0	0	30.0	mV	
8		Voltage gain 1	V14-2	O	O											1 kHz 100 mVp-p				14		Output AC measurement	20.3	23.3	26.3	dB
9		Voltage gain 2	V14-3		O	O										1 kHz 100 mVp-p				14		Output AC measurement	20.3	23.3	26.3	dB
10		Voltage gain difference	V14-4																	14	V15-4=V15-2-V15-3		-3.0	0	3.0	dB
11	TE amplifier	Maximum output amplitude L	V14-5	O	O				O					310 mV					14		Output DC measurement		—	-1.9	V	
12		Maximum output amplitude H	V14-6		O	O				O				310 mV					14		Output DC measurement	1.9	—		V	
13		Offset voltage 1	V13-1																	13	Input GND	Output DC measurement	-35	0	35	mV
14		Voltage gain 1	V13-2					O								1 kHz 140 mVp-p				13		Output AC measurement	21.9	24.9	27.9	dB
15	APC	Voltage gain 2	V13-3						O						1 kHz 140 mVp-p				13		Output AC measurement	21.9	24.9	27.9	dB	
16		Voltage gain difference	V13-4																	13	V13-4=V13-2-V13-3		-3.0	0	3.0	dB
17		Maximum output amplitude H	V13-5					O	O					270 mV						13		Output DC measurement	1.9	—	—	V
18		Maximum output amplitude L	V13-6						O	O				270 mV						13		Output DC measurement	—	—	-1.9	V
19	APC	Output voltage 1	V3-1											2.0 V	1.3 V			230 μ A	3		Output DC measurement	—	-1.7	-0.3	V	
20		Output voltage 2	V3-2											2.0 V	1.3 V			410 μ A	3		Output DC measurement	-1.5	0	1.1	V	
21		Output voltage 3	V3-3											2.0 V	1.3 V			590 μ A	3		Output DC measurement	0.6	2.0	—	V	
22		Output voltage 4	V3-4											0.5 V	1.3 V			0 μ A	3	LD OFF	Output DC measurement	2.1	2.3	—	V	
23		Maximum output amplitude	V3-5								O				2.0 V	1.3 V			0 μ A	3	I2=0.8 mA	Output DC measurement	—	—	0	V

* O in the SW conditions represents the ON state.

Measurement No.	Measurement item	Symbol	SW conditions										Bias conditions							Measurement pin	Description of I/O waveform and measurement method	Min.	Typ.	Max.	Unit							
			1	2	3	4	5	6	7	8	9	10	E1	E2	E3	E4	AC1	AC2	I1													
24	60 % limit	V3-6	O	O	O	O					O							50 mV	2.0 V		3.8 V/1.3 V					700 μA	3	Level control : 60 % (E4 : 4 V) -Level control OFF (E4 : 0.5 V)	-2950	-2350	-1150	mV
25	40 % limit	V3-7	O	O	O	O					O							50 mV	2.0 V		3.3 V/1.3 V					700 μA	3	Level control : 40 % (E4 : 2.5 V) -Level control OFF (E4 : 0.5 V)	-1620	-1120	-120	mV
26	-60 % limit	V3-8																	2.0 V		3.8 V/1.3 V		100 kHz 1.6 Vp-p	170 μA	3	Level control : -60 % (E4 : 4 V) -Level control OFF (E4 : 0.5 V)	1550	2350	2800	mV		
27	-40 % limit	V3-9																	2.0 V		1.8 V/1.3 V		100 kHz 1.6 Vp-p	170 μA	3	Level control : -40 % (E4 : 2.5 V) -Level control OFF (E4 : 0.5 V)	598	1098	1598	mV		
28	Hold characteristics	V1-1																		4 V/1 V	3.8 V/1.3 V				1	HOLD OFF → ON (t=0 ms) Level control 60 % → OFF (t=10 ms) V (t=100 ms)-V (t=0 ms)	-10	-2	0	mV		
29	Response characteristics 1	V1-2																		1 V	3.8 V/1.3 V				1	HOLD OFF Level control 60 % → OFF (t=0 ms) (V (t=1 ms)-V (t=0 ms))/(steady value-V (t=0 ms))	98	—	100	%		
30	Response characteristics 2	V1-3																		1 V	3.8 V/1.3 V				1	HOLD OFF Level control OFF → 60 % (t=0 ms) (V (t=1 ms)-V (t=0 ms))/(steady value-V (t=0 ms))	98	—	100	%		
31	Center output voltage	V12-1																							12	Output DC measurement	-100	—	100	mV		

* O in the SW conditions represents the ON state.

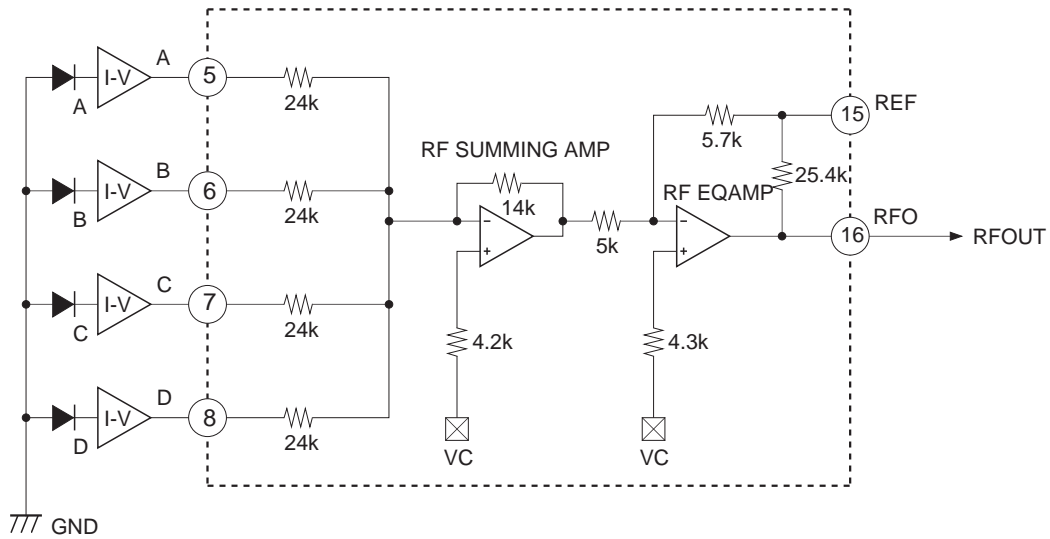
Electrical Characteristics Measurement Circuit



Description of Functions

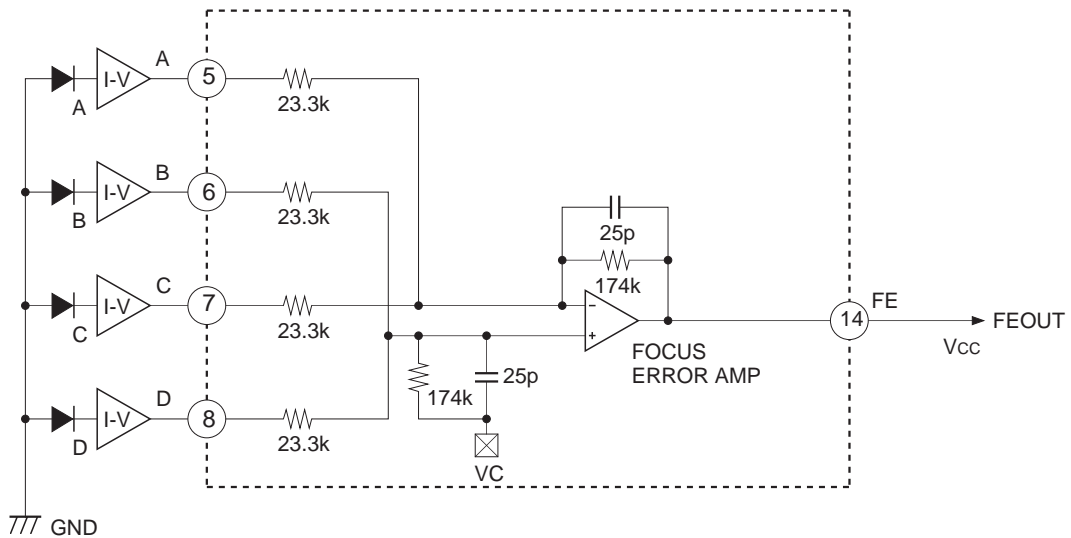
RF Amplifier

Each signal current from the photodiodes A, B, C and D is I-V converted, and input to Pins 5, 6, 7 and 8. These signals are added by the RF summing amplifier and equalized by the RF equalizing amplifier and then output to Pin 16. When the RF signal is equalized, an equalizing circuit is added to Pin 15.



Focus Error Amplifier

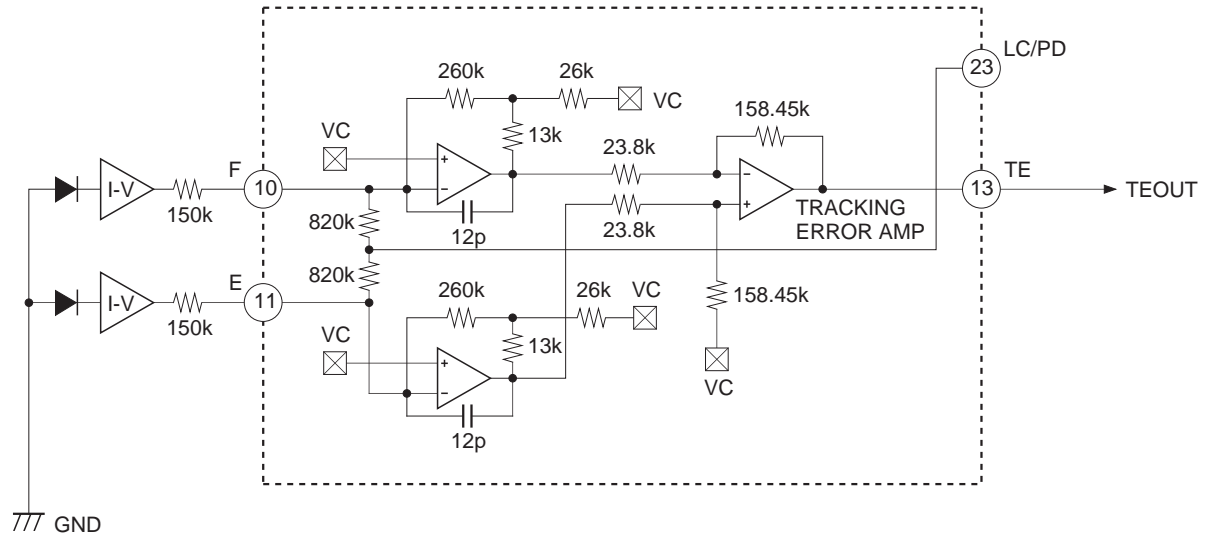
The operation of $(B+D)-(A+C)$ is performed and the signal is output to Pin 14.



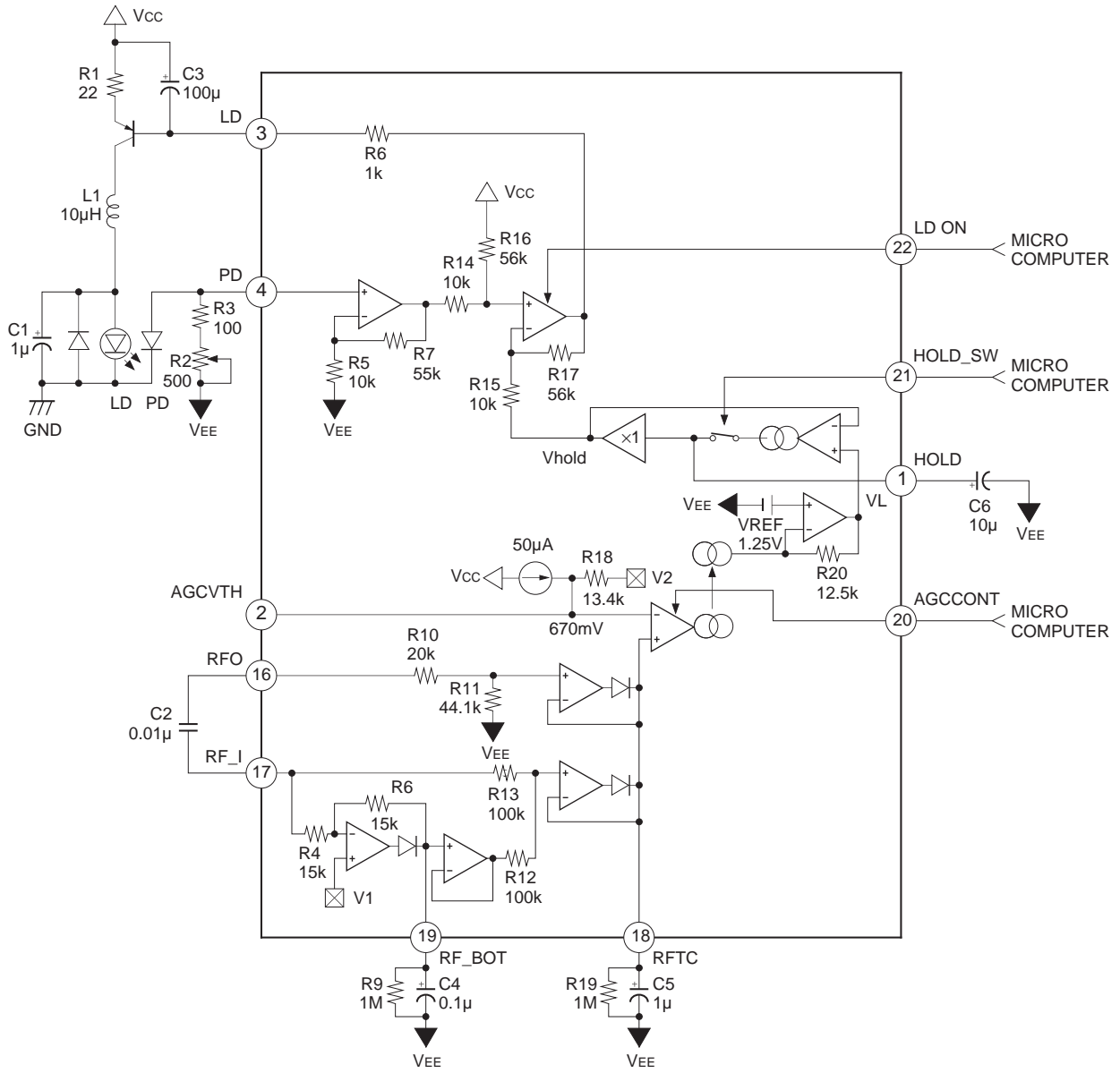
Tracking Error Amplifier

Each signal current from the photodiodes E and F is I-V converted and input to Pins 10 and 11 via an input resistor which determines the gain. The signal is amplified by the gain amplifier, operated by the tracking error amplifier and then the (F-E) signal is output to Pin 13.

Pin 23 can be used as a bias for LC when connected to VCC and as a bias for PD IC when left open.



APC & Laser Power Control



- APC

When the laser diode is driven by a constant current, the optical power output has extremely large negative temperature characteristics.

The APC circuit is used to maintain the optical power output at a constant level.

The laser diode current is controlled according to the monitor photodiode output.

APC is set to ON by connecting the LD ON pin to Vcc ; OFF by connecting it to VEE.

- Laser Power Control (LPC)

The RF level is stabilized by attaching an offset to the APC VL and controlling the laser power in sync with the RF level fluctuations.

The RFO and RF_I levels are compared and the larger of the two is smoothed by the RFTC's external CR.

This signal is then compared with the reference level.

The laser power is controlled by attaching an offset to VL according to the results of comparison with the reference level.

Set the reference level to 670 mV. (center voltage reference)

When the reference level is changed, connect the external resistor to the AGCVTH pin (Pin 2). The reference level can be lowered by connecting the resistor between Pin 2 and the center output voltage or between Pin 2 and Vcc.

The AGCCONT pin (Pin 20) is used to switch the level of the laser power control circuit ; OFF, ON (laser power limit of 40 %) and ON (laser power limit of 60 %).

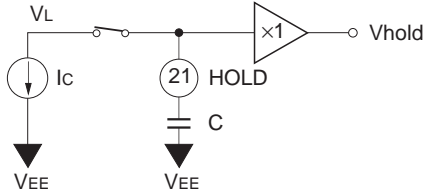
The HOLD_SW pin (Pin 21) is used to switch the hold ON and OFF for the VL signal. Set this pin to ON so as not to follow the fluctuation of the RF signal.

AGCCONT	LPC	LPC limit	VL variable range
L (VEE)	OFF	—	Approximately 1.27 V
M (VC or OPEN)	ON	40 %	Approximately 1.27 V±350 mV
H (Vcc)	ON	60 %	Approximately 1.27 V±570 mV

The hold ON/OFF operation is approximately as follows.

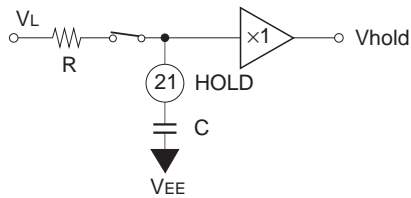
1. HOLD : Operation for OFF

(a) $|V_L - V_{hold}| \geq 2V_T$ ($V_T \approx 26 \text{ mV}$)



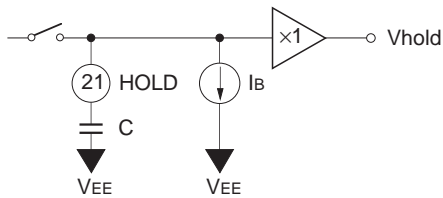
(typ.) $I_c = 500 \mu\text{A}$ ($V_L < V_{hold}$)
 $-500 \mu\text{A}$ ($V_L > V_{hold}$)

(b) $|V_L - V_{hold}| < 2V_T$



(typ.) $R = 105 \Omega$

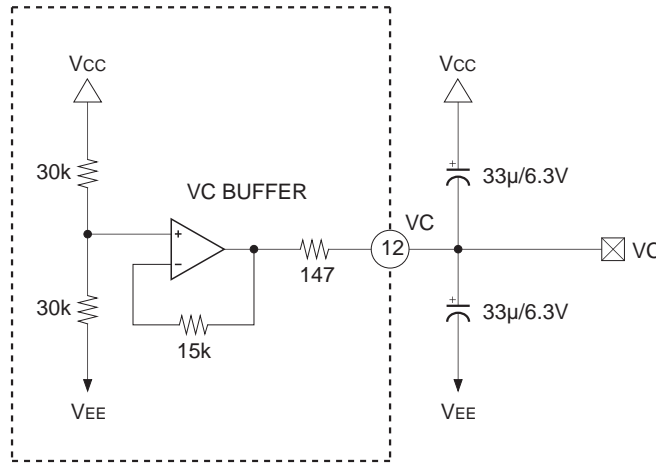
2. HOLD : Operation for ON



(typ.) $I_b = 6.5 \text{ nA}$

Center Voltage Generation Circuit

This circuit provides the center potential when this IC is used at single power supply. The maximum current is approximately ± 3 mA. The output impedance is approximately 147 Ω . Connect this circuit to GND when used at dual power supply.



Notes on Operation

1. Power supply

The CXA2568M can be used either at dual power supply or single power supply. The table below shows the connection of power supply for each case.

	VCC	VEE	VC
Dual power supply	+power supply	-power supply	GND
Single power supply	Power supply	GND	OPEN

2. Laser power control

The RF level is stabilized by attaching an offset to the APC VL and controlling the laser power in sync with the RF level fluctuations. Therefore, use this circuit in the state where the focus servo is applied.

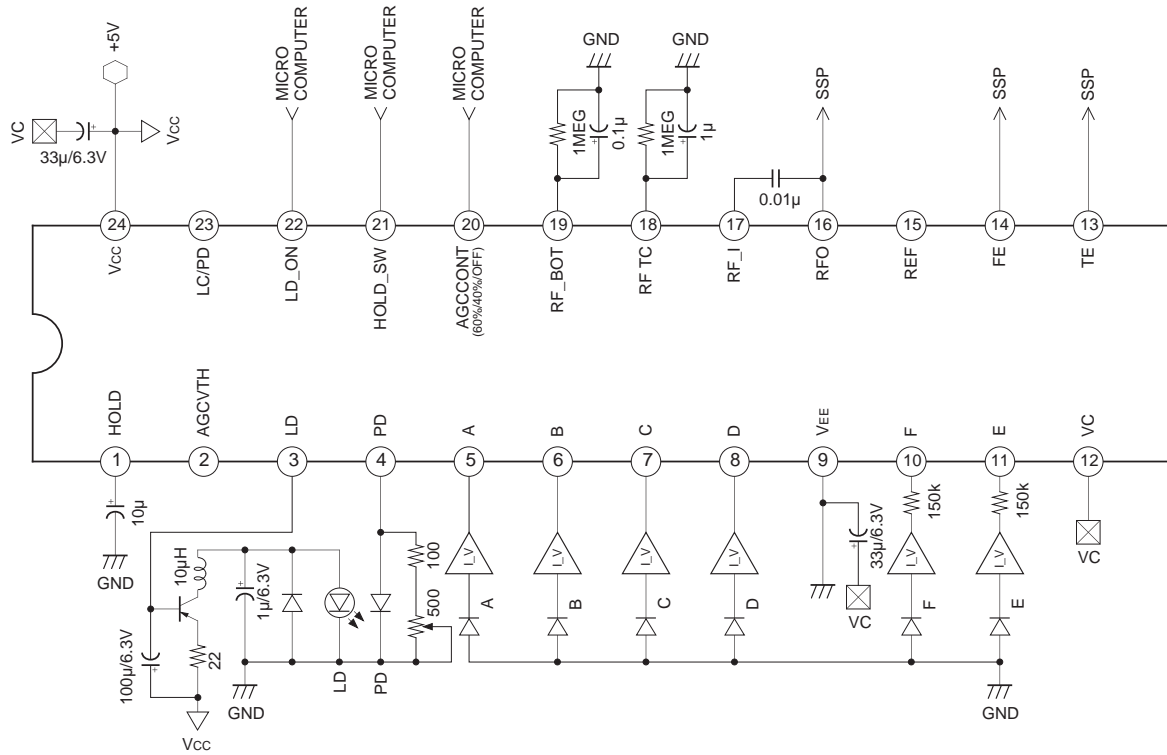
The laser life is shortened by increasing the laser power when the less light is reflected from the disc. It is recommended that the typical laser power value is set lower to maintain the laser life.

The laser power limit value depends on the external circuit. Select the laser power limit setting considering the external conditions.

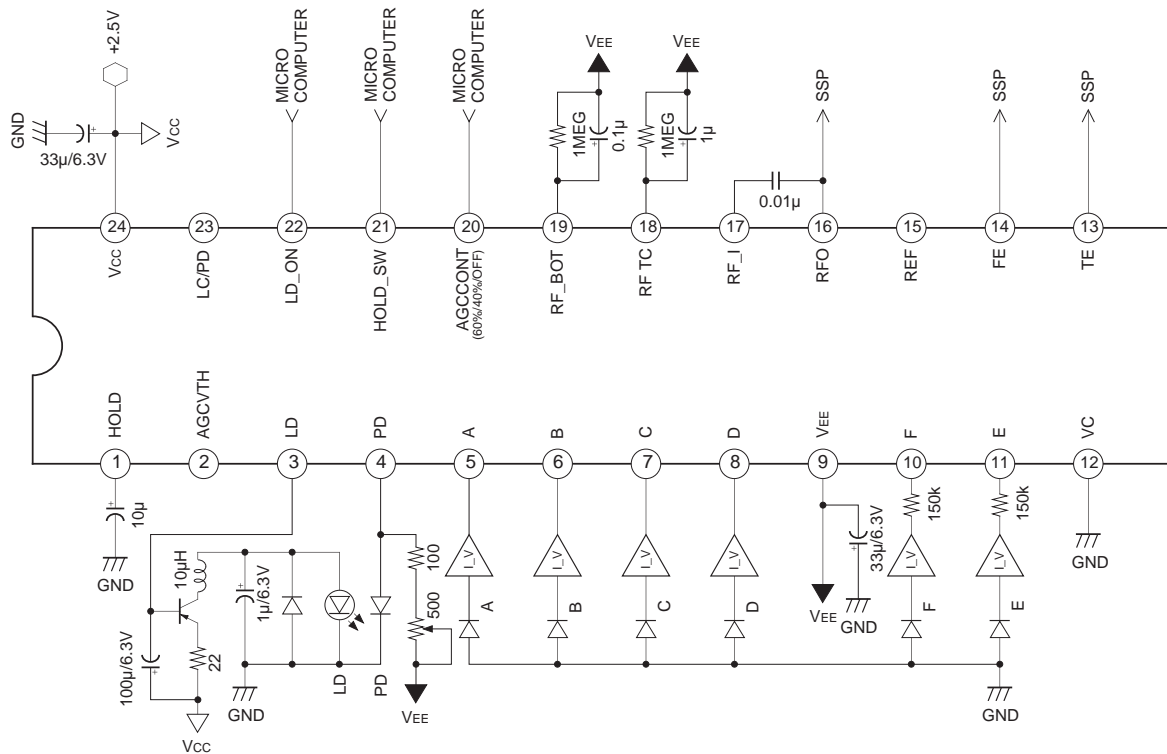
Take care of the laser maximum ratings when using the laser power control circuit.

Application Circuit

- For single power supply +5 V



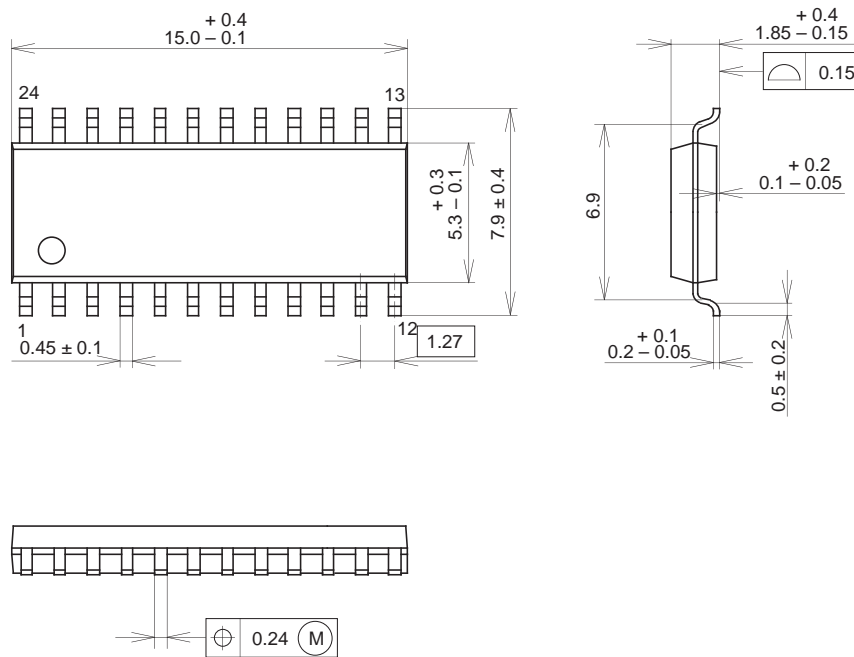
- For dual power supply +2.5 V



Application circuits shown are typical examples illustrating the operation of the devices. Sony cannot assume responsibility for any problems arising out of the use of these circuits or for any infringement of third party patent and other right due to same.

Package Outline Unit : mm

24PIN SOP (PLASTIC)



PACKAGE STRUCTURE

SONY CODE	SOP-24P-L01
EIAJ CODE	SOP024-P-0300
JEDEC CODE	_____

MOLDING COMPOUND	EPOXY RESIN
LEAD TREATMENT	SOLDER PLATING
LEAD MATERIAL	42/COPPER ALLOY
PACKAGE MASS	0.3g